Introducing
Sockets and Hardware for LGA 1156 Processors

TE Connectivity's surface mount LGA socket was designed for use with Intel's® Core™ i7 LGA 1156 processor. The contacts have solder balls for surface mount onto the PCB, while the top side provides a cantilever beam interface to the package. The integrated lever mechanism (ILM) generates the Z-axis compression load. A robust bolster plate eliminates PCB bowing during compression. The sockets have been validated to Intel Design Guides.

TE connectivity

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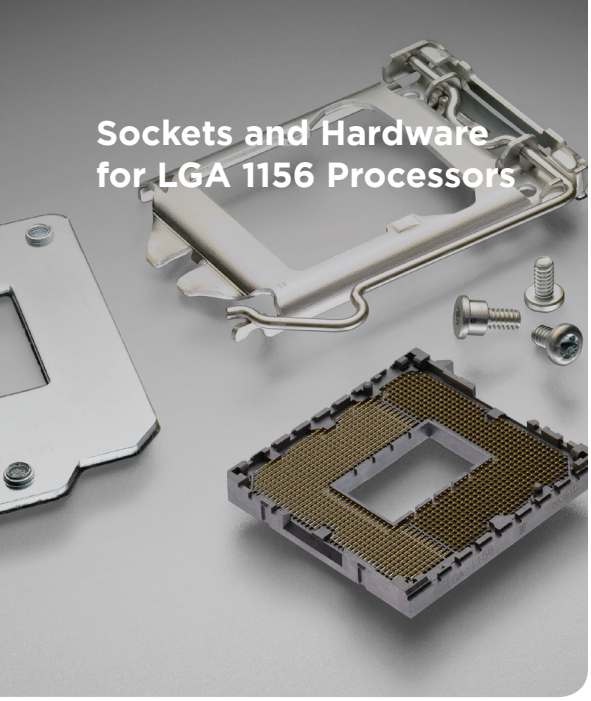

KEY FEATURES

- 1156 contacts with a 0.914mm x 0.914mm grid.
- Available with 15 Gold or Gold flash contact plating.
- Socket housing facilitates efficient soldering to the PCB board.
- Socket is supplied with a cap to facilitate vacuum pick and place.
- Backplates are available in zinc or nickel plating.
- ILM, screws and backplate must be ordered separately. Kits are also available for ease in ordering.
- Each ILM assembly requires two ILM screws and one ILM shoulder screw.

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3-1773455-8 CIS-MS-05/2011

APPLICATIONS

- Desktop computers
- Low end servers

ELECTRICAL

- Low level bulk contact resistance: 22 milliohms max avg.
- Insulation resistance: 800 milliohms min. @ 500 VDC

MECHANICAL

- Nominal Deflection: .45 mm
- Durability: 30 cycles
- Package mating and unmating operation force of lever: 49N (5kgf) maximum

MATERIALS

- Socket assembly
  Contact: Copper Alloy, gold plating at contact area on nickel under plating.
  Base housing: High temperature thermoplastic UL94V-0
  Cap: High temperature thermoplastic UL94V-0
- ILM load plate and lever: Stainless steel
- ILM frame, ILM screw and shoulder screw: Steel
- ILM Insulator: Polypropylene
- Backplate assembly: Steel, zinc or nickel plated
- Backplate Insulator: Polypropylene

APPLICATIONS AND SPECIFICATION

- Application specification 114-5444
- Instruction sheet 411-78321
- Product Spec 108-78586

PRODUCT OFFERINGS

Part Number	Description	Plating
2040540-1	LGA 1156 Socket	15 Gold
2040540-2	LGA 1156 Socket	Gold Flash
2013882-1	ILM Assembly	
2013882-2	ILM Assembly with ILM screws	
2013883-1	Back plate assembly	Zinc
2013883-2	Back plate assembly	Nickel
2013884-1	Shoulder Screw	
2040979-1	ILM Screw	

ILM/Back Plate Kits

Part No.	2013882-1 ILM Assembly	2013884-1 Shoulder Screw	2040979-1 ILM Screw	2013883-1 Back Plate Assembly - Zinc Plated	2013883-2 Back Plate Assembly - Ni Plated	
2069838-1	1	1	2	1	0	Qty per kit
2069838-3	0	1	2	1	0	
2069838-4	1	1	2	0	1	
2069838-5	0	1	2	0	1	